

Date: 03/16/2011

PMP5624REVB BOM

COUNT	RefDes	Value	Description	SIZE	Part Number	MFR
1	C1	330uF	PosCap, 10V, sizeD, 3A	7343(D)	10TPE330M	Sanyo
1	C10	33nF	Capacitor, Ceramic, 25V, X7R, 10%	0603	Std	Std
1	C11	330pF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
1	C12	3.3nF	Capacitor, Ceramic, 50V, X7R, 15%	0603	Std	Std
1	C14	100nF	Capacitor, Ceramic, vvV, [temp], [tol]	0805	GRM40yyyxxxKvv	muRata
4	C2, C3, C6, C13	22uF	Capacitor, Ceramic, 10V, X5R, 15%	1210	C3225X5R1A226MT	TDK
1	C4	470uF	PosCap, 6.3V, sizeD, 4.4A	7343(D)	6TPD470M	Sanyo
1	C5	OPEN	PosCap, sizeD, 4.4A	7343(D)	6TPD470M	Sanyo
3	C7, C8, C9	1uF	Capacitor, Ceramic, 16V, X5R, 15%	0603	Std	Std
1	D1	PDS1045	Diode, Schottky, 10A, 45V	Power DI	PDS1045	Diodes Inc.
1	D2	BAT54	Diode, Schottky, 200-mA, 30-V	SOT23	BAT54	Vishay-Liteon
2	J1, J2	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
2	J3, J4		Header, 3-pin, 100mil spacing, (36-pin strip)	0.100 x 3"	PTC36SAAN	Sullins
1	L1	4.7uH	Inductor, Dual Winding, 4.7uH, 8.25A, 9.17 milliohm	0.492 x 0.492	DRQ127-4R7-R	Cooper
1	Q1	CSD25401Q3	MOSFET, P-Ch, -20V, 8.7 milliOhm	QFN3.3X3.3mm	CSD25401Q3	TI
1	Q2	CSD16323Q3	MOSFET, N-Ch, 25V, 5.6 milliOhm	QFN3.3x3.3 mm	CSD16323Q3	TI
4	R1, R2, R5, R9	0	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R10	10K	Resistor, Chip, 1/16-W, 1%	0603	Std	Dale
1	R12	100K	Resistor, Chip, 1/16-W, 1%	0603	Std	Dale
1	R13	49.9	Resistor, Chip, 1/16-W, 1%	0603	Std	Dale
1	R14	24.9K	Resistor, Chip, 1/16-W, 1%	0603	Std	Dale
3	R3, R4, R8	DNP	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R6	124K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
2	R7, R11	1K	Resistor, Chip, 1/16-W, 1%	0603	Std	Dale
4	TP1, TP2, TP3, TP6	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
3	TP4, TP5, TP7	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	TPS43000	IC, Multi-topology High Frequency, PWM Controller	TSSOP-16	TPS43000PW	Texas Instruments

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk ("**") cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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